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## New modularizing CPU baffle

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## **New modularizing CPU baffle**

### Abstract

Every computer system has different components layout placement, the CPU baffle is one of the approaches to cooling the processor. Disclosed is a new idea for modularizing the CPU baffle. Assembling by two plastic parts which can fulfill product thermal performance required by different direction combination. The new design also can save some tooling money investment.

### Description

This disclosure relates to the field of computers. Such as server systems.

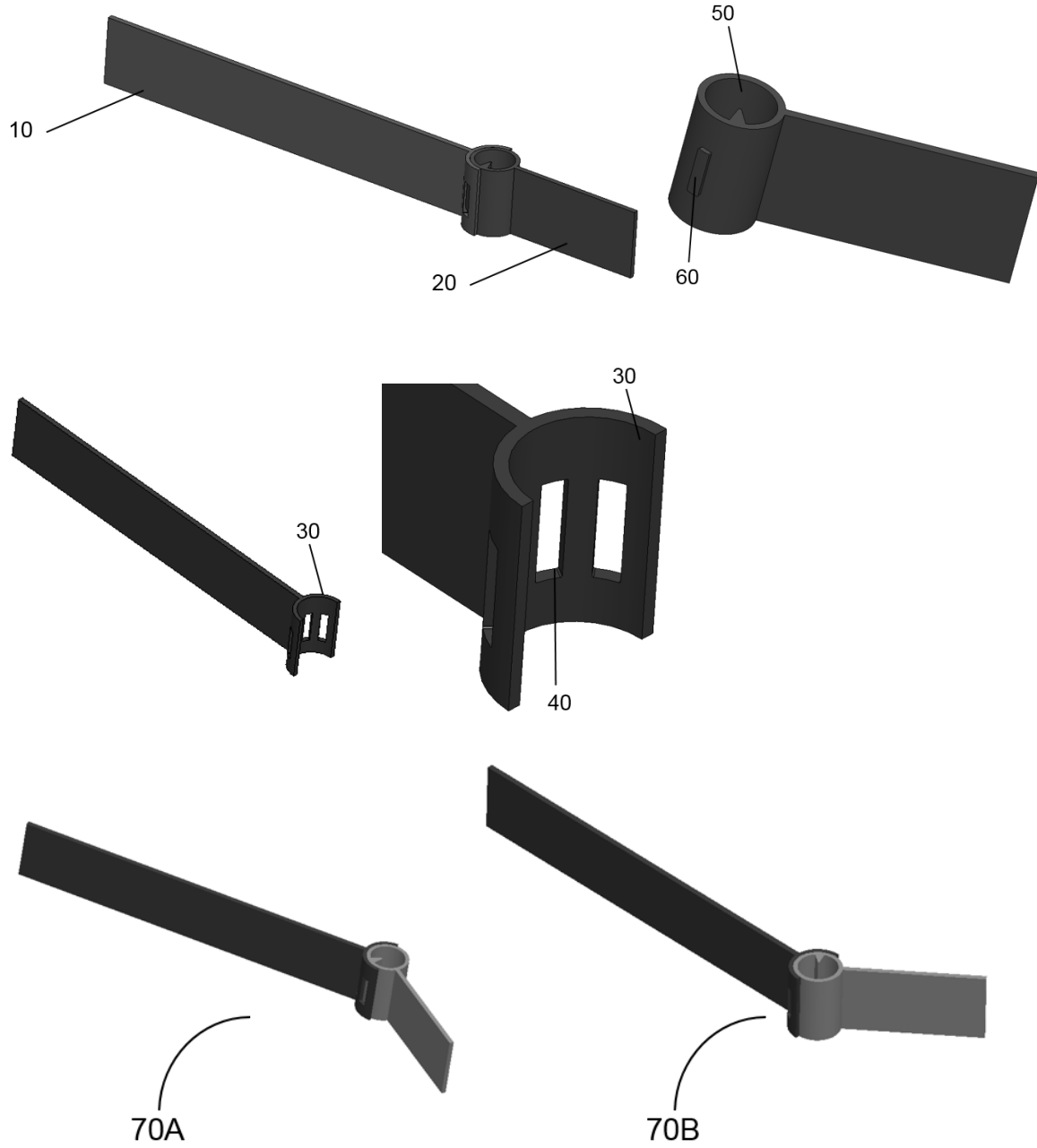
A technique is disclosed that facilitates to develop the CPU cooling in a computer system.

In many computer systems, for example, industrial standard server systems, lots of hardware parts had been modularizing well, the purpose of modularizing those part not only to save the cost but also largely reduce the development schedule. This new modularizing CPU baffle idea can save tooling money investment, and help the company to reach the goal to overcome the cost pressure from the stockholder or high management.

Prior computer system develops their own specific cooling baffle base on the different layout. The specific part will only be used on the certain product.

According to the present disclosure, and as understood with reference to the figure, The new idea can separate into two plastic parts. The first part baffle 10 can be fixed on somewhere where needs cooling. The second part baffle 20, which can be hook and fix with the baffle 10. The idea of the baffle 10 is a dome shape 30 on the front end with some cavities/holes 40. The baffle 20 is also a dome shape 50 on the front side with a rib feature 60. This rib 60 can snap on with the cavities 40 in multiple different directions. In view 70A, this is one of the combinations to fix the baffle10 with the baffle20. In view 70B, this is the other one of the combination to fix the baffle10 with the baffle20.

The disclosed new modularizing CPU baffle can advantageously save some tooling money investment by using the common part for different products. The different assembly combination also can provide the design flexibility to fulfill different direction type which product required.



Disclosed by:

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